



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D
<i>* : Required Field</i>			

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2016-05-04
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Rossana Bonaccorso	<b>Representative Title</b>	ADG MD Champion
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
<b>Legal Statement</b>	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STPS10150CFP	HTUI*Z38P02R	A	SHENZHEN B/E	2016-05-04
Amount		UoM	Unit type	ST ECOPACK Grade
1900.00		mg	Each	ECOPACK2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
NAC	NAC	NAC		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
SIP	10.2-16.15-4.5	3	THROUGH HOLE	
Comment	TO 220 ISOL FULL PACK 0.5 AB			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-17th December 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	HTUI*Z38P02R					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	3.181	mg	supplier	die	Silicon (Si)	7440-21-3		2.994	mg	941232	1576
				supplier	metallization	Aluminium (Al)	7429-90-5		0.124	mg	38969	65
				supplier	metallization	Titanium (Ti)	7440-32-6		0.003	mg	944	2
				supplier	metallization	Tungsten (W)	7440-33-7		0.004	mg	1257	2
				supplier	metallization	Nickel (Ni)	7440-02-0		0.013	mg	4085	7
				supplier	Passivation	Silicon Oxide	7631-86-9		0.018	mg	5657	9
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.001	mg	314	1
				supplier	back side metallization	Gold (Au)	7440-57-5		0.004	mg	1257	2
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.020	mg	6285	11
				Leadframe	Copper & Its alloys	614.126	mg	supplier	alloy	Copper (Cu)	7440-50-8	
supplier	alloy	Iron (Fe)	7439-89-6						0.278	mg	453	146
supplier	alloy	Iron Phosphide (FeP)	26508-33-8						0.508	mg	827	267
supplier	metallization	Nickel (Ni)	7440-02-0						8.816	mg	14355	4640
supplier	metallization	Phosphorus (P)	12185-10-3						0.055	mg	90	29
Soft solder	Solder	3.039	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	2.902	mg	954919	1527
				supplier	solder	Silver (Ag)	7440-22-4		0.076	mg	25008	41
				supplier	solder	Tin (Sn)	7440-31-5		0.061	mg	20073	32
Bonding wires	Other inorganic materials	6.020	mg	supplier	wire	Aluminium (Al)	7429-90-5		6.020	mg	1000000	3168
Encapsulation	Other Organic Materials	1267.768	mg	supplier	mold compound	Quartz	14808-60-7		887.437	mg	700000	467072
				supplier	mold compound	Silica, vitreous	60676-86-0		95.083	mg	75000	50044
				supplier	mold compound	Epoxy resin	25068-38-6		177.487	mg	140000	93414
				supplier	mold compound	phenol resin	29690-82-2		88.744	mg	70000	46707
				supplier	mold compound	metal hydroxide	21645-51-2		12.678	mg	10000	6673
supplier	mold compound	carbon black	1333-86-4		6.339	mg	5000	3336				
Connections coating	Solder	5.866	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		5.866	mg	1000000	3087